

Features

- Low On-Resistance
- Low Gate Threshold Voltage
- Low Input Capacitance
- Fast Switching Speed
- **Lead Free By Design/RoHS Compliant (Note 2)**
- **ESD Protected Gate**
- **"Green" Device (Note 4)**
- **Qualified to AEC-Q101 standards for High Reliability**

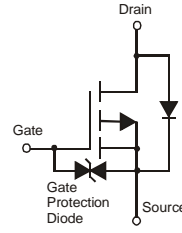


ESD protected

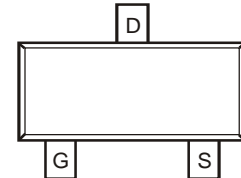


TOP VIEW

SC59



EQUIVALENT CIRCUIT



Internal Schematic

Mechanical Data

- Case: SC59
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture sensitivity: Level 1 per J-STD-020C
- Terminals: Finish — Matte Tin annealed over Copper leadframe. Solderable per MIL-STD-202, Method 208
- Terminal Connections: See Diagram
- Marking Information: See Page 3
- Ordering & Date Code Information: See Page 3
- Weight: 0.014 grams (approximate)

Maximum Ratings @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Characteristic	Symbol	Value	Unit
Drain-Source Voltage	V_{DSS}	-30	V
Gate-Source Voltage	V_{GSS}	± 20	V
Drain Current (Note 1) Steady State	I_D	-0.7	A
Pulsed Drain Current (Note 3)	I_{DM}	-2.8	A

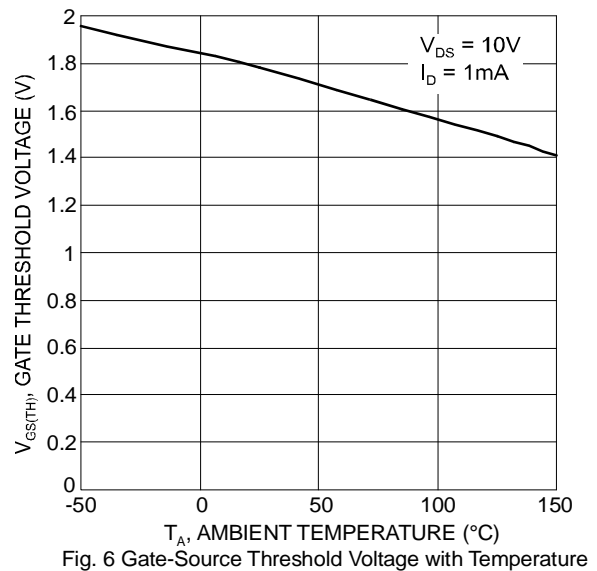
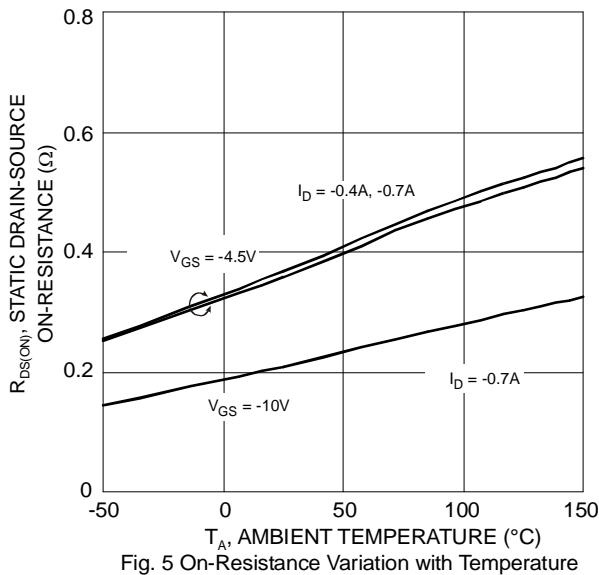
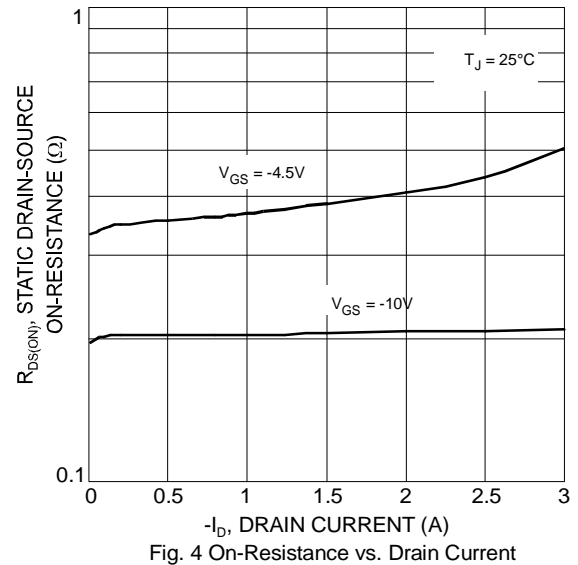
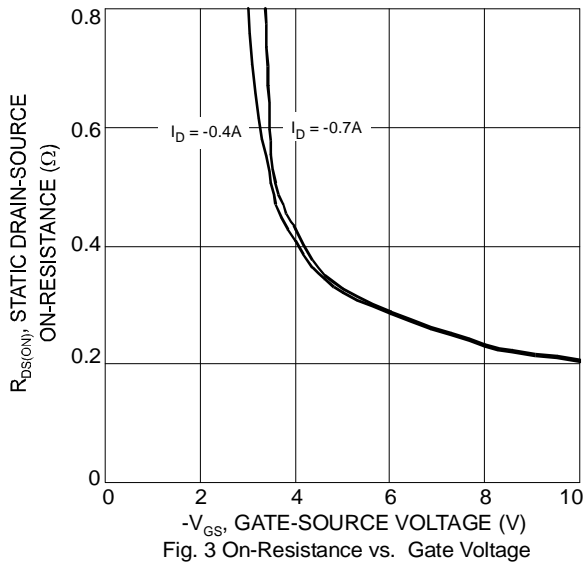
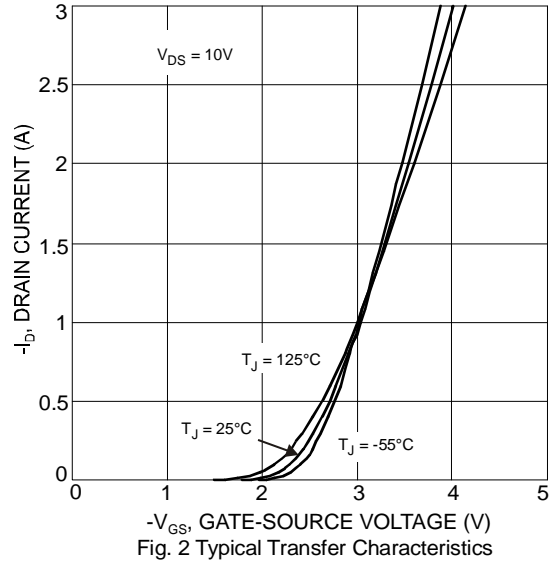
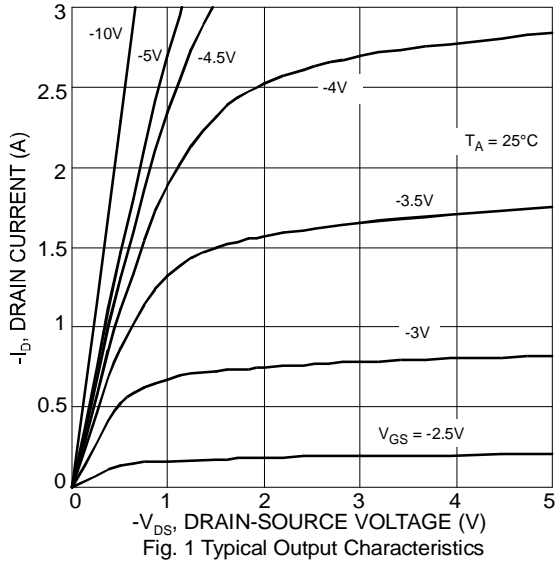
Thermal Characteristics @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Characteristic	Symbol	Value	Unit
Total Power Dissipation (Note 1)	P_d	500	mW
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	250	$^\circ\text{C}/\text{W}$
Operating and Storage Temperature Range	T_j, T_{STG}	-65 to +150	$^\circ\text{C}$

Electrical Characteristics @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 5)						
Drain-Source Breakdown Voltage	BV_{DSS}	-30	—	—	V	$V_{GS} = 0\text{V}, I_D = -250\mu\text{A}$
Zero Gate Voltage Drain Current	I_{DSS}	—	—	-10	μA	$V_{DS} = -30\text{V}, V_{GS} = 0\text{V}$
Gate-Body Leakage	I_{GSS}	—	—	± 10	μA	$V_{GS} = \pm 20\text{V}, V_{DS} = 0\text{V}$
ON CHARACTERISTICS (Note 5)						
Gate Threshold Voltage	$V_{GS(th)}$	-1.0	—	-3.0	V	$V_{DS} = -10\text{V}, I_D = -1.0\text{mA}$
Static Drain-Source On-Resistance	$R_{DS(ON)}$	—	0.20 0.35	0.25 0.45	Ω	$V_{GS} = -10\text{V}, I_D = -0.4\text{A}$ $V_{GS} = -4.5\text{V}, I_D = -0.4\text{A}$
Forward Transfer Admittance	$ Y_{fs} $	—	1	—	S	$V_{DS} = -10\text{V}, I_D = -0.4\text{A}$
Diode Forward Voltage (Note 5)	V_{SD}	—	-0.8	-1.1	V	$V_{GS} = 0\text{V}, I_S = -0.7\text{A}$
DYNAMIC CHARACTERISTICS						
Input Capacitance	C_{iss}	—	160	—	pF	$V_{DS} = -10\text{V}, V_{GS} = 0\text{V}$ $f = 1.0\text{MHz}$
Output Capacitance	C_{oss}	—	120	—	pF	
Reverse Transfer Capacitance	C_{rss}	—	50	—	pF	
SWITCHING CHARACTERISTICS						
Turn-On Delay Time	$t_{D(ON)}$	—	10	—	ns	$V_{DD} = -10\text{V}, I_D = -0.4\text{A},$ $V_{GS} = -5.0\text{V}, R_{GEN} = 50\Omega$
Turn-Off Delay Time	$t_{D(OFF)}$	—	25	—	ns	
Turn-On Rise Time	t_r	—	25	—	ns	
Turn-Off Fall Time	t_f	—	40	—	ns	

- Notes:
1. Device mounted on FR-4 PCB.
 2. No purposefully added lead.
 3. Pulse width $\leq 10\mu\text{s}$, Duty Cycle $\leq 1\%$.
 4. Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com/products/lead_free/index.php.
 5. Short duration pulse test used to minimize self-heating effect.



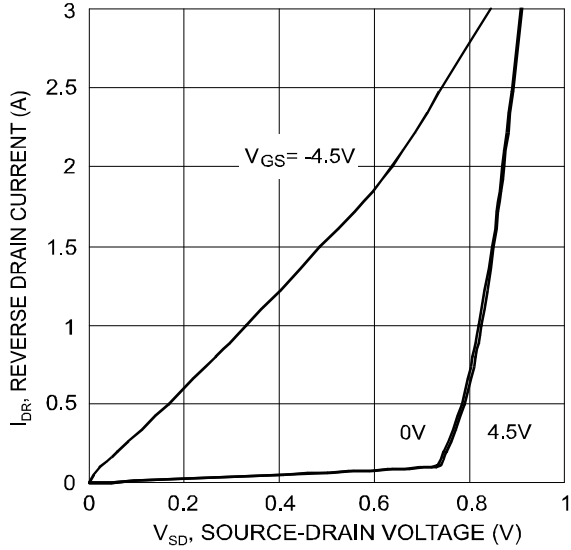


Fig. 7 Reverse Drain Current vs. Source-Drain Voltage

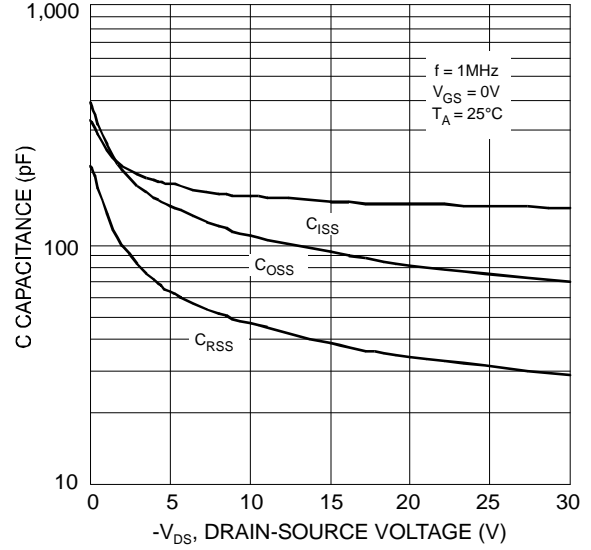


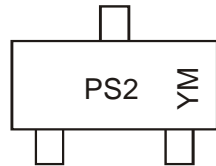
Fig. 8 Typical Total Capacitance

Ordering Information (Note 6)

Part Number	Case	Packaging
DMP3030SN-7	SC59	3000/Tape & Reel

Notes: 6. For packaging details, go to our website at <http://www.diodes.com/datasheets/ap02007.pdf>.

Marking Information



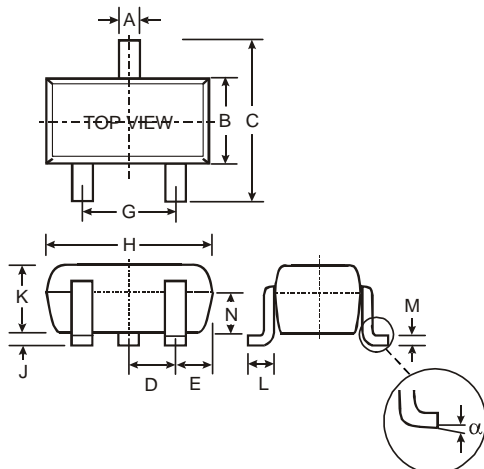
PS2 = Product Type Marking Code
 YM = Date Code Marking
 Y = Year ex: T = 2006
 M = Month ex: 9 = September

Date Code Key

Year	2006	2007	2008	2009	2010	2011	2012
Code	T	U	V	W	X	Y	Z

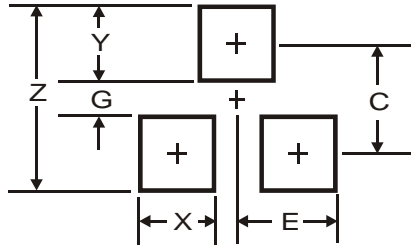
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

Package Outline Dimensions



SC59		
Dim	Min	Max
A	0.35	0.50
B	1.50	1.70
C	2.70	3.00
D	0.95	
E	—	
G	1.90	
H	2.90	3.10
J	0.013	0.10
K	1.00	1.30
L	0.35	0.55
M	0.10	0.20
N	0.70	0.80
α	0°	8°
All Dimensions in mm		

Suggested Pad Layout



Dimensions	Value (in mm)
Z	4.0
G	1.2
X	0.9
Y	1.4
C	2.6
E	0.95

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